

Workpackage 8 - Calorimetry and Particle ID

Roman Pöschl



Roberto Ferrari



AIDAinnova 2nd Project Review Meeting – June 2024



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Task 8.1. Coordination and Communication (CNRS-IJCLab, INFN-PV)

- Since last Annual Meeting: Katja Chair of Governing Board

Task 8.2. Towards next generation highly granular calorimeters

- Integration aspects of highly granular calorimeters (DESY, DMLAB, CNRS-IJCLab, CNRS-LLR, CNRS-LPNHE, JGU, CERN, TAU, FZU, IFIC)
- Future Liquid Noble Gas Calorimeters (CERN, CNRS-IJCLab, CUNI)

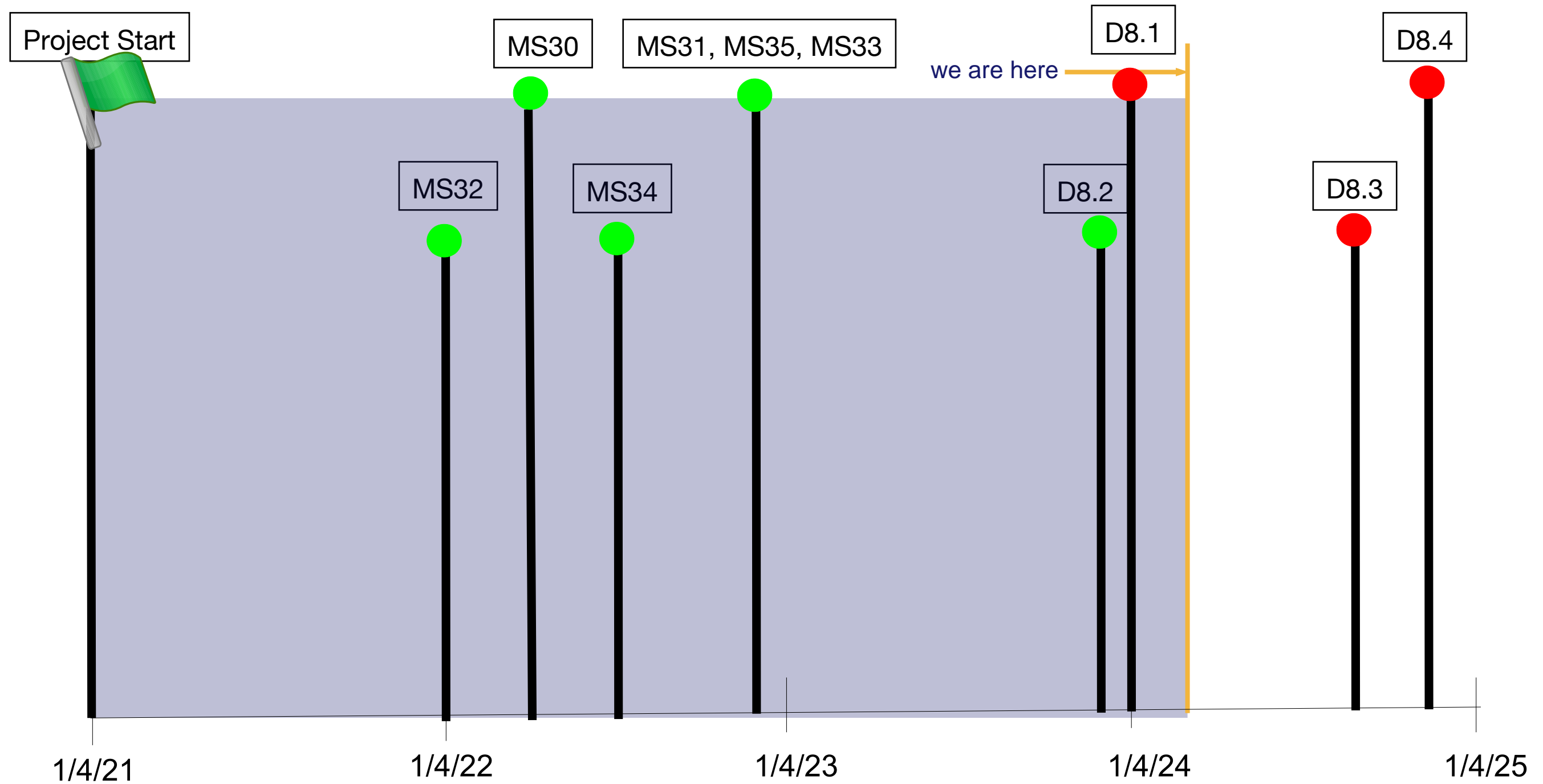
Task 8.3. Innovative calorimeters with optical readout

- Crystal detectors (CERN, FZU, VU, INFN-PG, INFN-LNF, INFN-TO)
- Large area scintillator detectors (MPP-MPG, DESY, INFN-BO, INFN-LNF, JGU)

Task 8.4. Innovative solid-state light sensors and highly-granular dual-readout fibre-sampling calorimetry

- Innovative SiPMs and future applications in PID detectors (JSI, INFN-PD, INFN-TO, CERN, FBK, UiB, FZU, FOTON)
- Development of highly-granular dual-readout fibre-sampling calorimeters (INFN-PV, INFN-MI, INFN-PI, INFN-BO, UOS, CAEN)

WP8 - Timeline



#MS	Description	Task	Due	Type	Lead
MS30	Conceptual design and technical specifications of DAQ interfaces for highly granular electromagnetic and hadronic calorimeters	8.2	M15	Report to StCom	DESY
MS31	Design and simulation of LAr readout electrode	8.2	M23	Report to StCom	CUNI
MS32	Test benches for testing detecting materials in picosecond and sub-picosecond domains.	8.3	M12	Specs data sheet	CERN
MS33	Design and test of scintillating tiles or strips with large active area suitable for large area detectors.	8.3	M15 → M23	Operational Testbenches	MPG-MPP
MS34	Definition of SiPM requirements and performance studies with simulations of different use cases.	8.4	M18	Report to StCom	JSI
MS35	Definition of the assembly method and of the ASIC specifications for a dual readout calorimeter.	8.4	M23	Report to StCom	INFN-MI

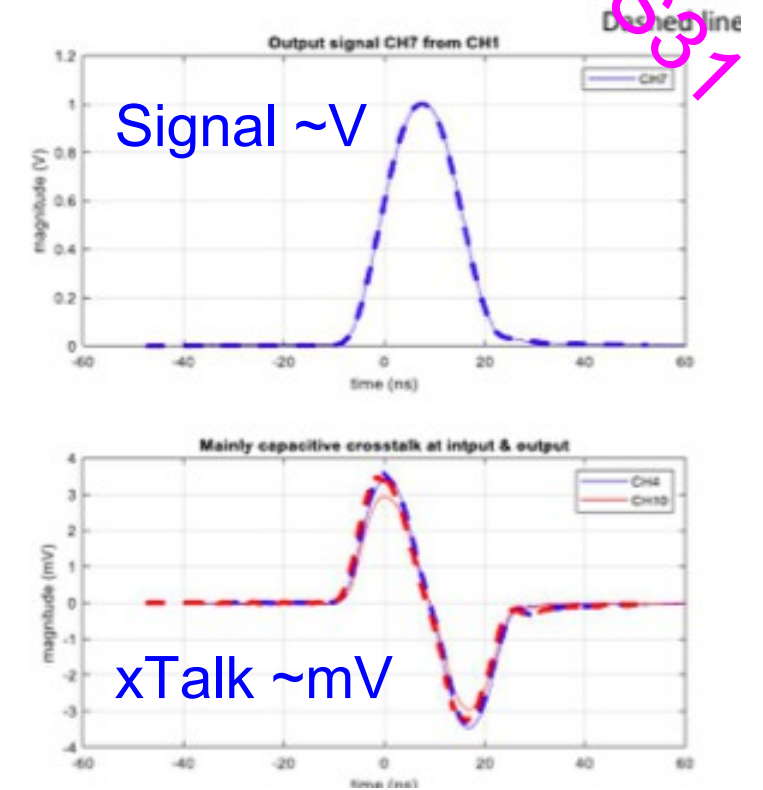
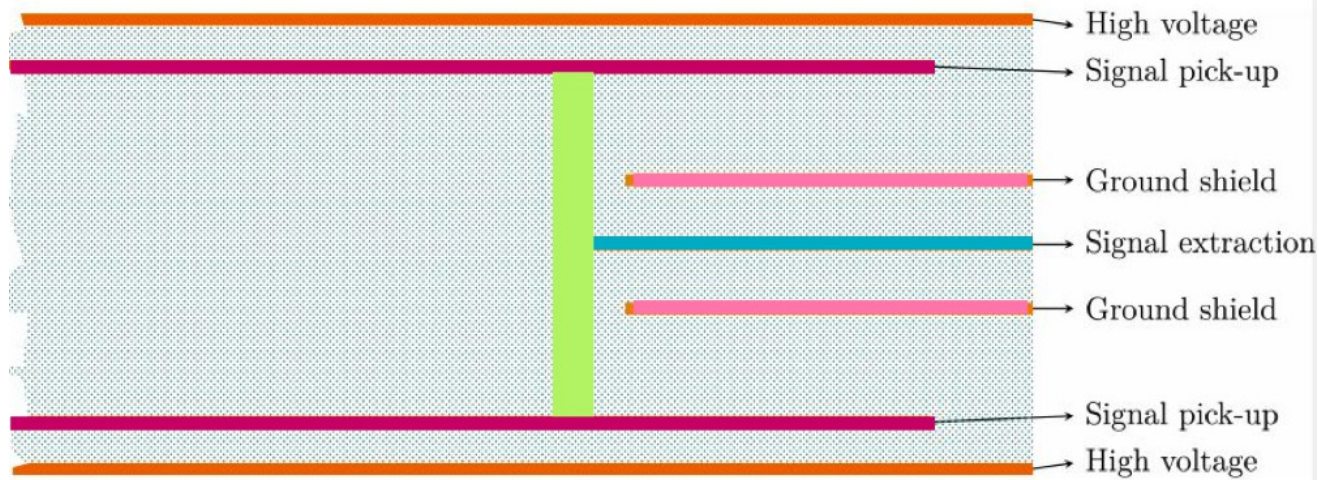
#D	Description	Task	LEad	Type	Dissemination	Due
D8.1	Demonstrator of a combined read-out system of highly granular electromagnetic and hadronic calorimeters	8.2	DESY	DEM	PU	M36
D8.2	Report on prototypes construction, performance and assessment of industrialisation	8.3	CERN	R	PU	M35
D8.3	Qualification of neutron irradiated SiPMs at different temperatures.	8.4	JSI	R	PU	M44
D8.4	Construction and qualification with beam of 10×10 cm ² , 2 m long, prototypes	8.4	INFN-MI	DEM	PU	M46

- All four deliverables due between M35 (29/2/24) and M46 (31/1/25)
- Will have to shift D8.1 by 6 months
 - Details see below

- **Regular Taskleader Meetings**
 - Among others: Reminder on publications and orientation to publication committee
 - Expect that number of publications will increase in coming months
- **WP8 Face-to-Face Meeting 2024 18/1/24**
 - <https://indico.cern.ch/event/1344030/>
- **Mailing lists**
 - AIDAinnova-WP8-Taskleaders@cern.ch contains all task leaders
 - AIDAinnova-WP8-Institutes@cern.ch contains one contact per group/institute
 - AIDAinnova-WP8-General@cern.ch with self-subscription, open for everyone who is interested

- D8.1 :
 - Demonstrator of a combined read-out system of highly granular electromagnetic and hadronic calorimeters” **was due in M36 (March, 2024)**
 - The development of common DAQ interfaces implies a knowledge/technological transfer from the SiW ECAL to the AHCAL
 - The process is started, but the board design, testing and operation are delayed
 - A technical issue prevents the delivery in due time:
 - **The SiW-ECAL wafer-PCB delamination problem needs to be solved before any further test can be made; it was raised as the highest priority on the path to the production of new ASUs.**
 - Details in backup
 - The delay of the deliverable by six months to M42 (September, 2024) allows for producing a few boards for a proof-of-principle test of the SiW-ECAL, which would then form the basis of the transfer to the AHCAL. A combined test of a couple of layers SiW-ECAL+AHCAL at DESY is foreseen for the 2nd half of 2024.
- Despite the delay there is still sizeable progress in the task (see backup)

- Development of a multilayer PCB
 - HV layer on both sides
 - Readout layer on both sides
 - Connected to signal trace

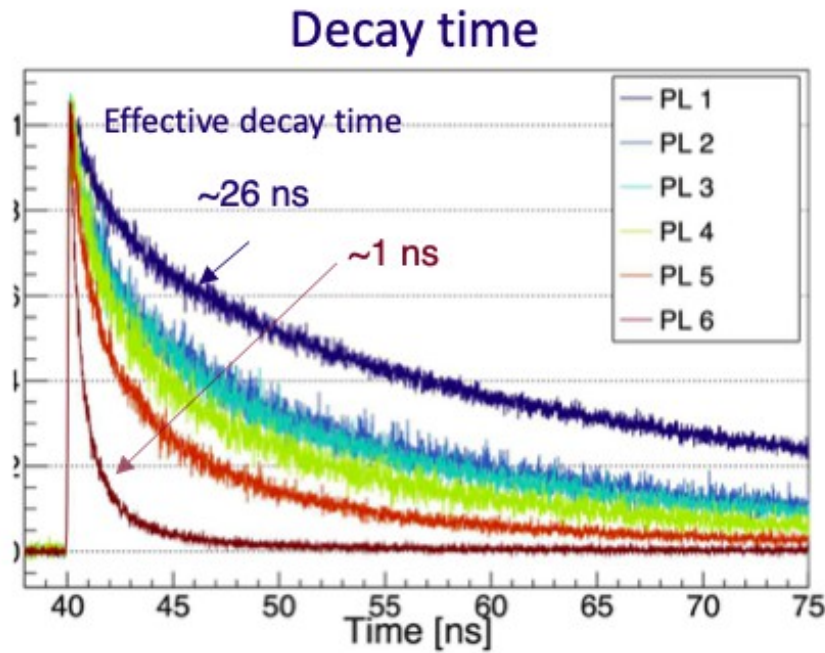
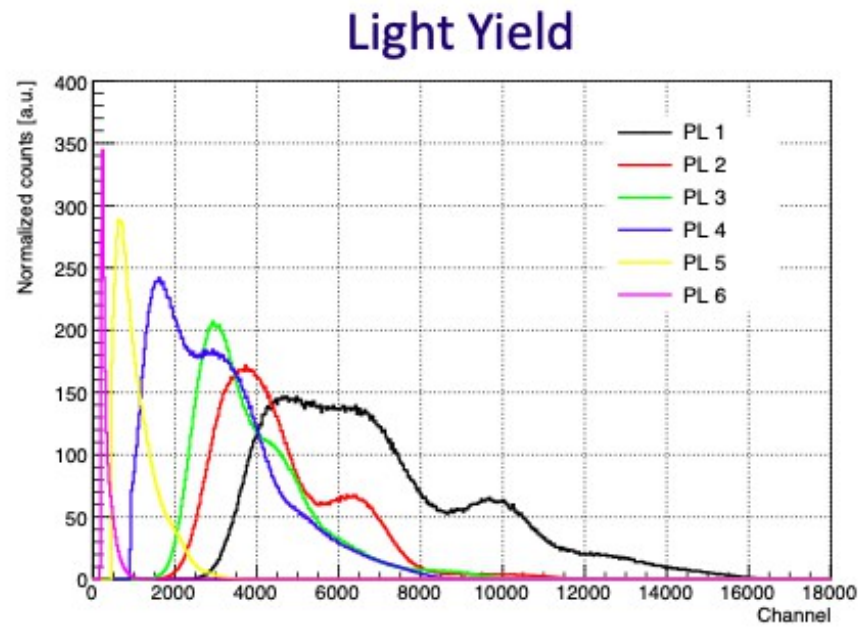
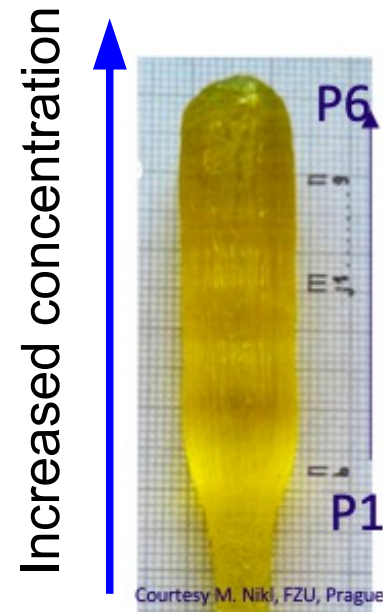


Challenges:

- One signal trace is economical solution to reduce signal traces
- Pick-up of signal from both sides increases S/N

- Control number of signal traces
 - => Xtalk? Seems to be well under control
- Big number of capacitances => Noise
 - Goal is 300 keV noise for 200 pF cell (S/N > 5)
 - FCC-ee allows for higher integration times
 - Cold electronics?

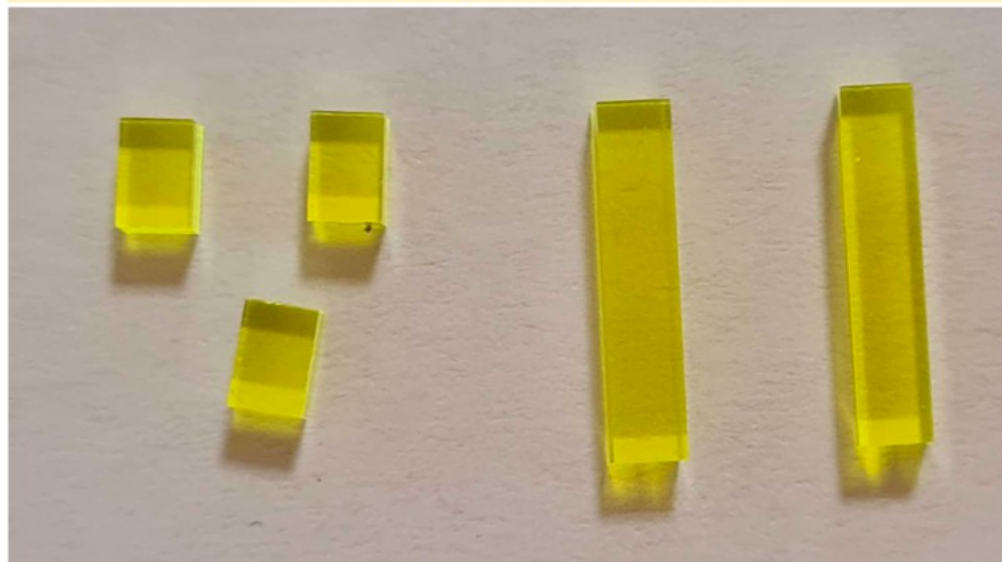
GAGG:Ce Xtal doped with Ce/Mg



D8.2

Decrease of decay time with increased doping (lower light output has no influence on time resolution)

GAGG Samples produced by CRYTUR



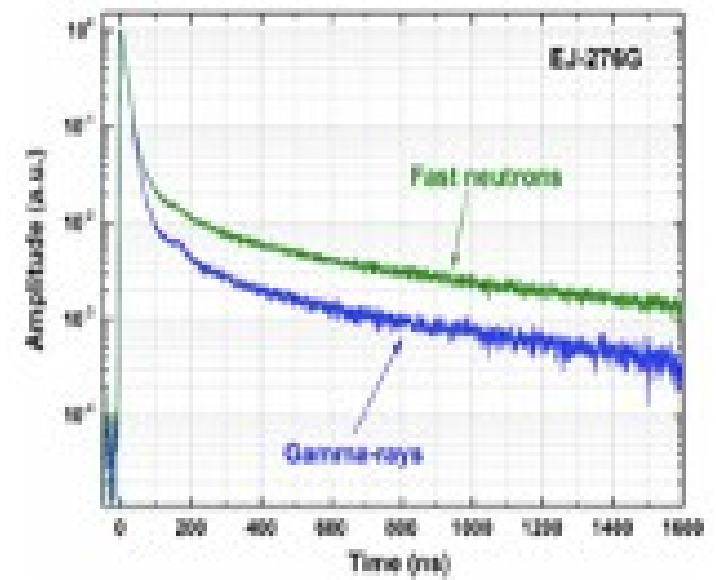
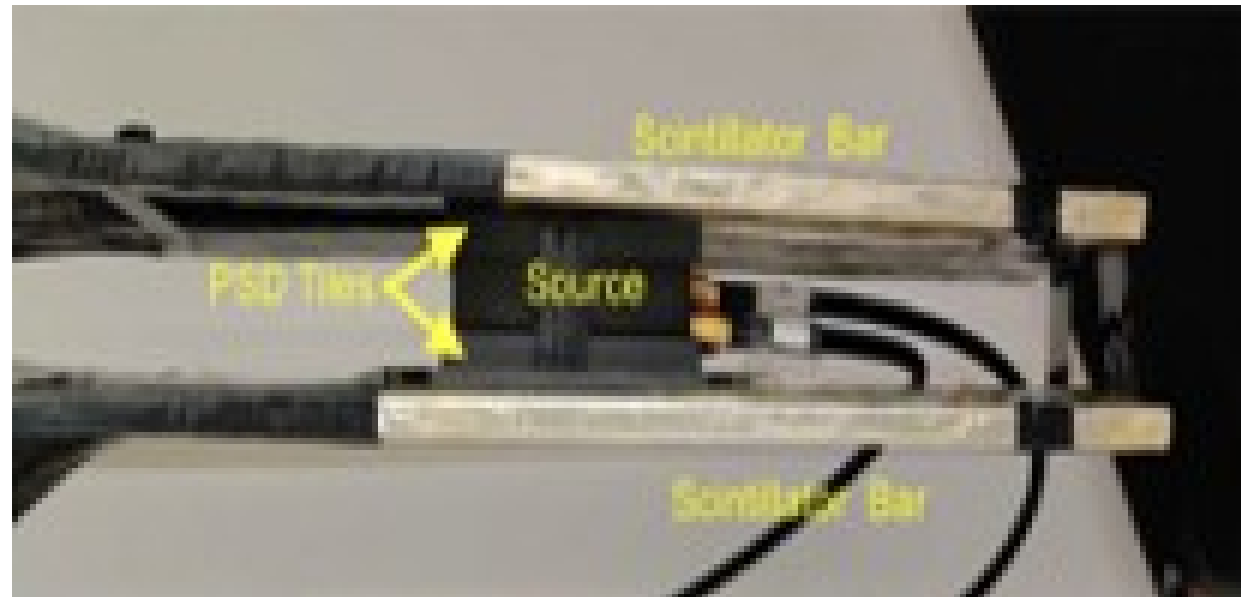
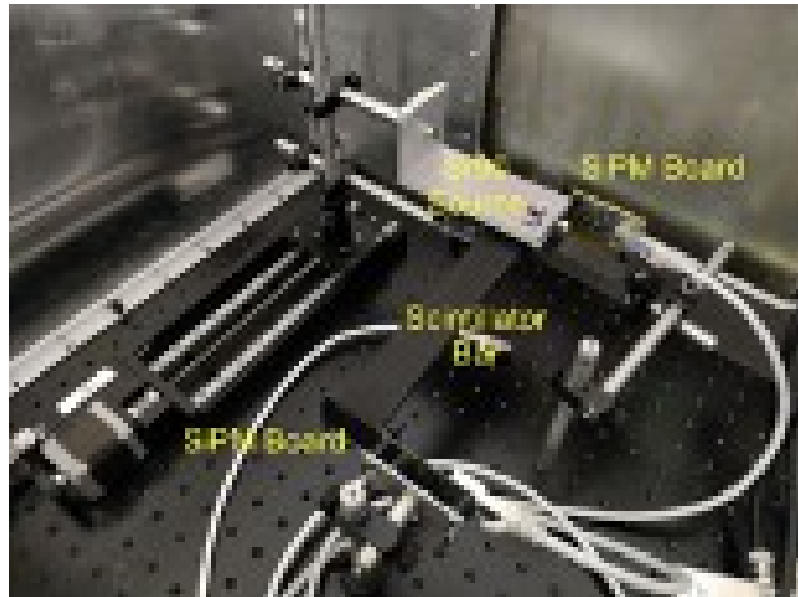
=> technology transfer

Industrial Czochralski growth in CRYTUR was adapted => able to grow first ingot: Ø 25mm, first task was to obtain HOMOGENEOUS COMPOSITION AND CHARACTERISTICS within the crystal body

MPI-MPP: Long scintillator bars

JGU: Neutron gamma discrimination using an AmBe source

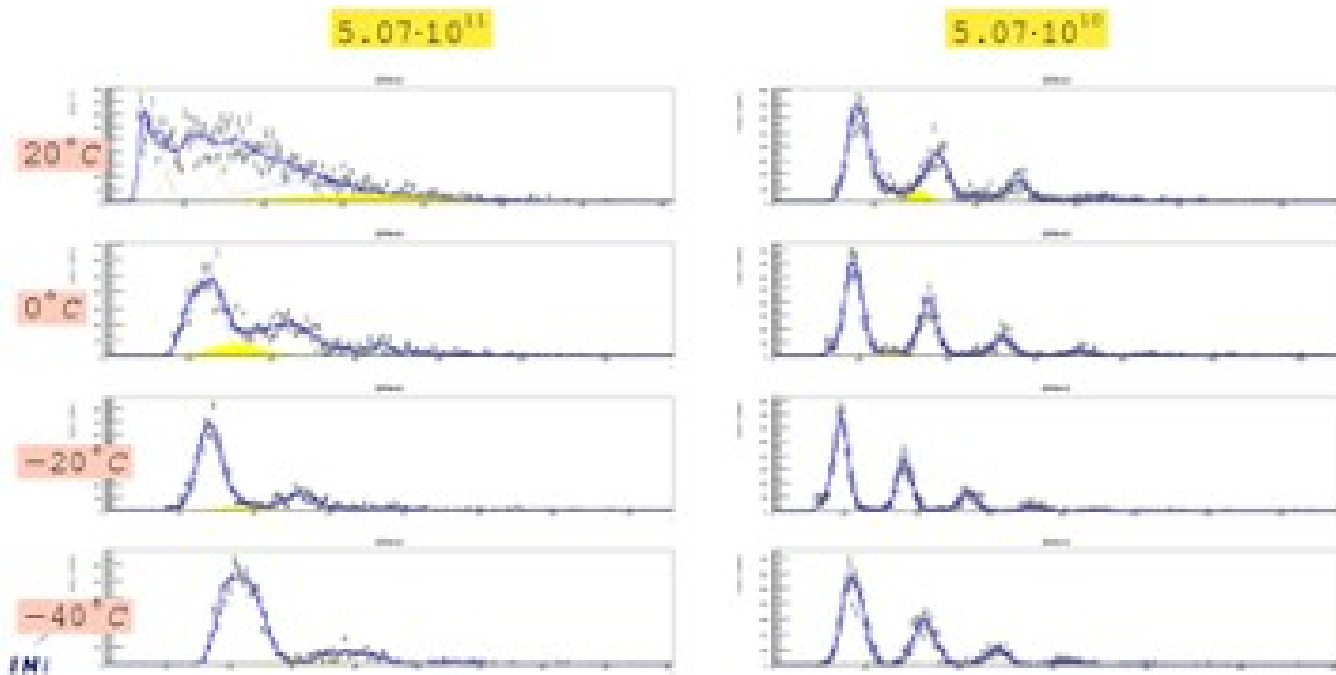
MS33



Left: Large (15x15 cm²) tile
 Right: Wall constructed from 15 large tiles

MS34

Standardised protocols
for SiPM characterisation
Toward “AIDAInnova Standard”

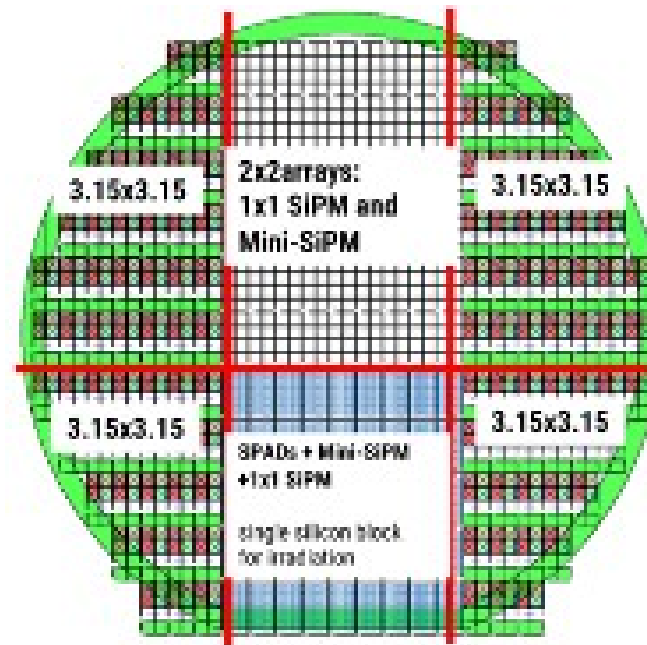


Hamamatsu SiPMs irradiated at different doses and at different operating temperatures

Developments with (semi) industrial partners

FBK (I)

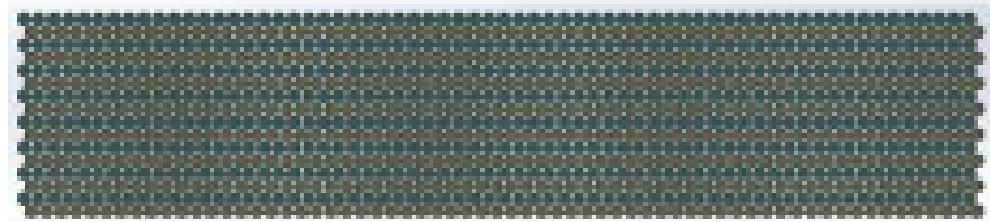
FOTON (CZ)



AIDAInnova funded production FBK NUV-HD SiPMs wafer composition



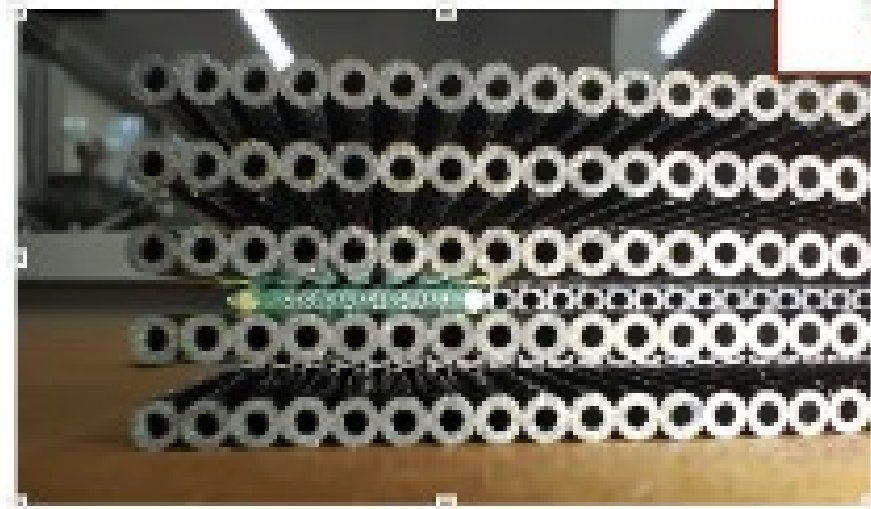
ADAPOWER 4100, adaptive power supply for SiPMs



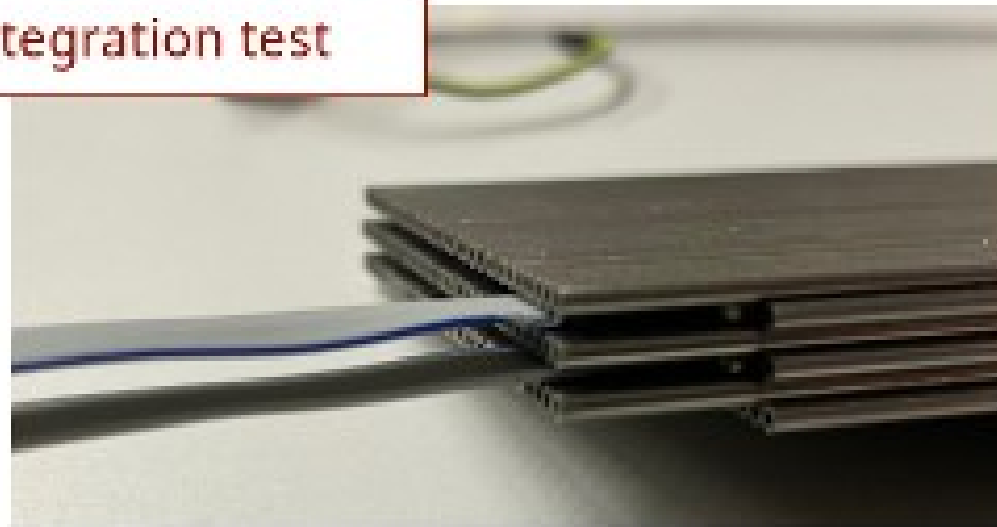
HiDRa minimodule (left)

assembled minimodules (right)

Mechanical test for mini-frontend board installation



Board-integration test



Need for compactness
triggered R&D on digital
SiPM (see backup)

- **WP8 on track**
 - All milestones have been achieved
 - First deliverable achieved
 - One deliverable delayed due to unforeseen technical problems
 - Solution will lead to new competences!
 - Two more deliverables between now and end of project on March 31st 2025

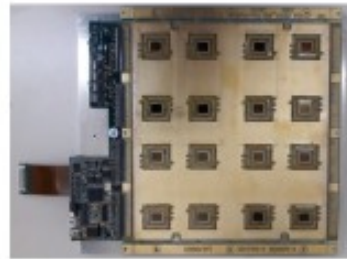
- **Time to harvest the results --> Publications !!!!**
 - 13 publications recorded in Zenodo portal
 - ... more to come

- **Education and outreach**
 - Material developed within AIDAinnova (and its predecessor AIDA-2020)
 - Used at instrumentation school
 - See OnTrack article in backup



FEV10, 11, 12

- BGA packaging
- Incremental modifications
- From v10 -> v12
- Main "Working horses" since 2014



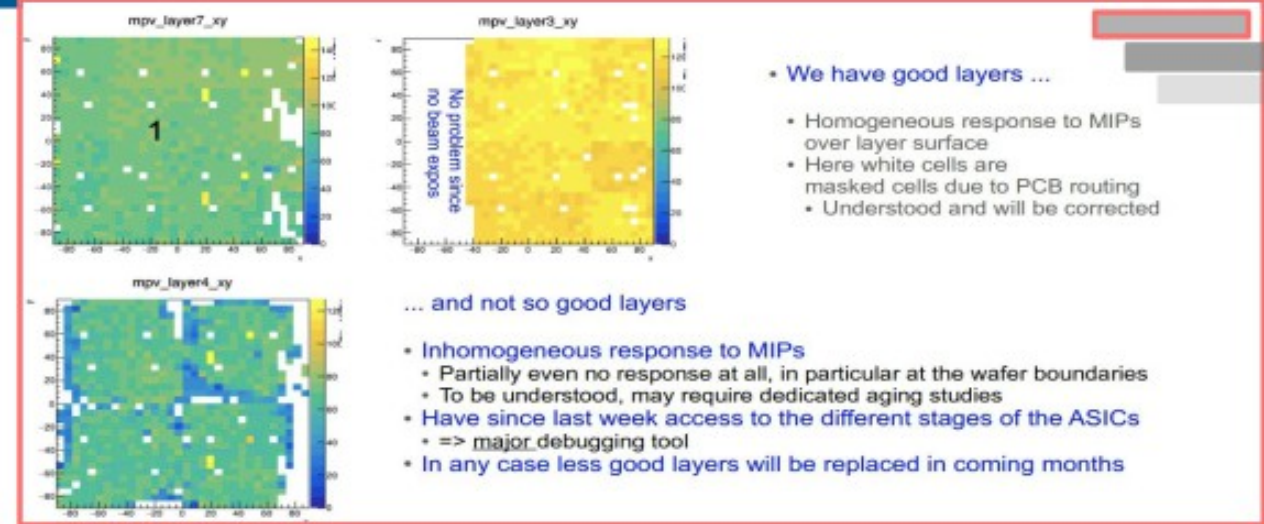
FEV-COB

- Chip-On-Board : ASICs wirebonded in cavities
 - Thinner than FEV with BGA
- Based on FEV11
 - External connectivity compatible



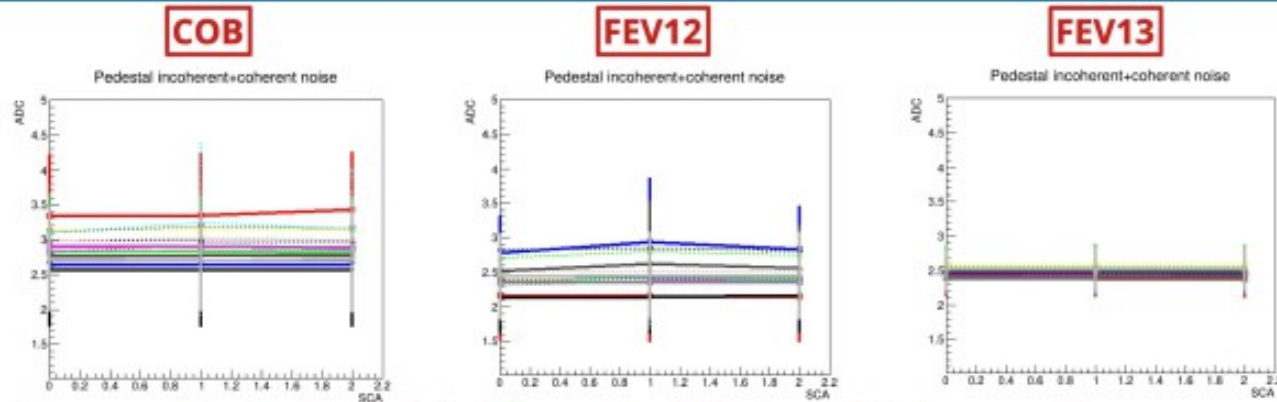
FEV13

- BGA packaging
 - Improved routing
 - Local power storage
 - Different external connectivity

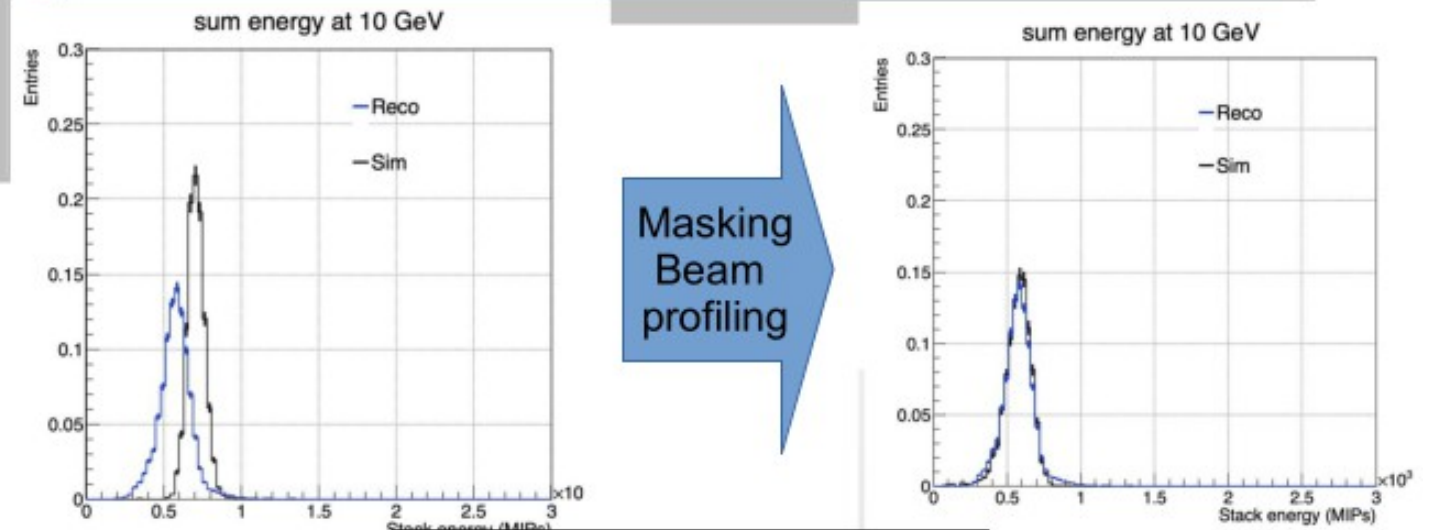


- We have good layers ...
- Homogeneous response to MIPs over layer surface
- Here white cells are masked cells due to PCB routing
- Understood and will be corrected

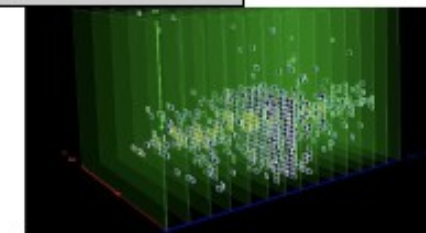
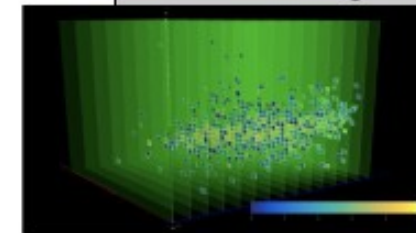
Pedestal widths, 1st memory cells, per asic



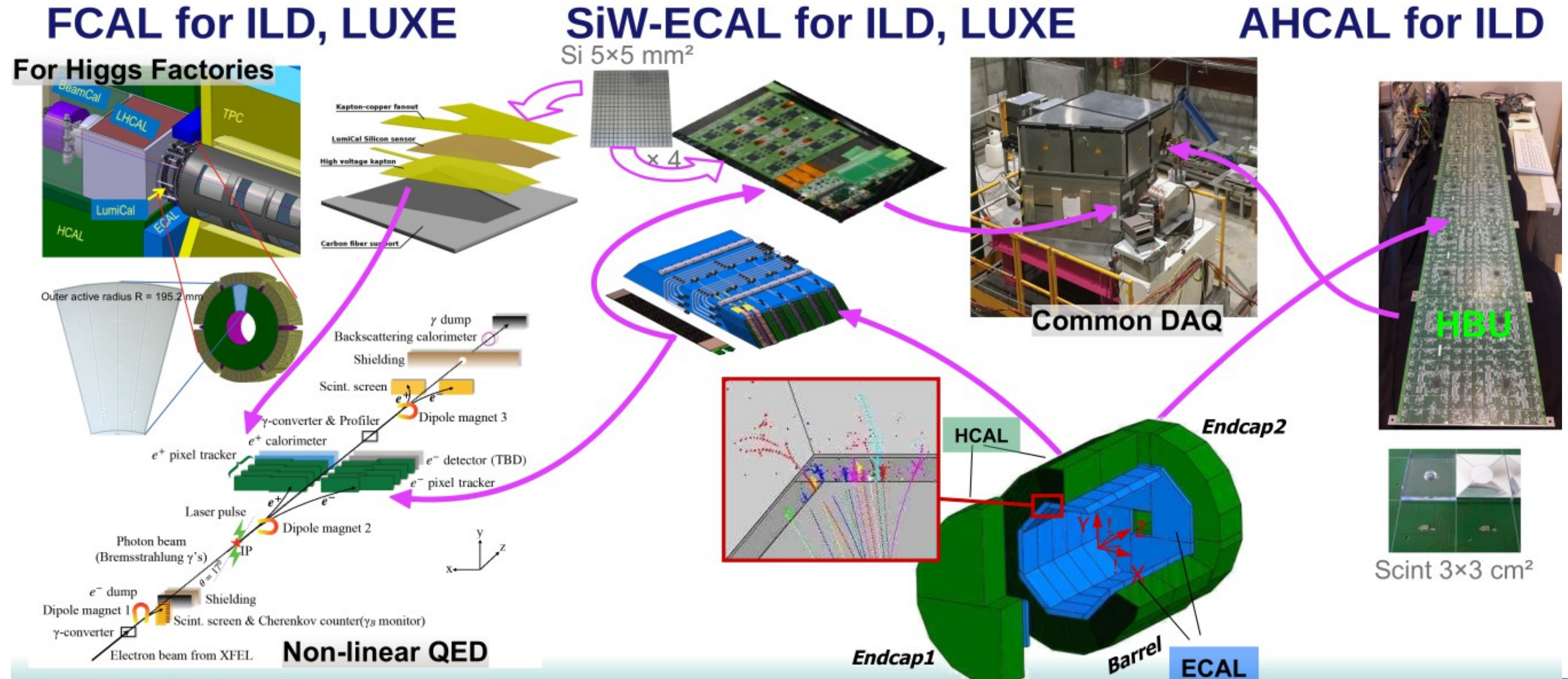
- (Average ± Standard Deviation) of Sigmas for all 64 channels in the same chip
- Latest PCBs, with optimized routing of power distribution shows better behavior
- Slightly larger spread on COB due to a near lack of decoupling capacitors



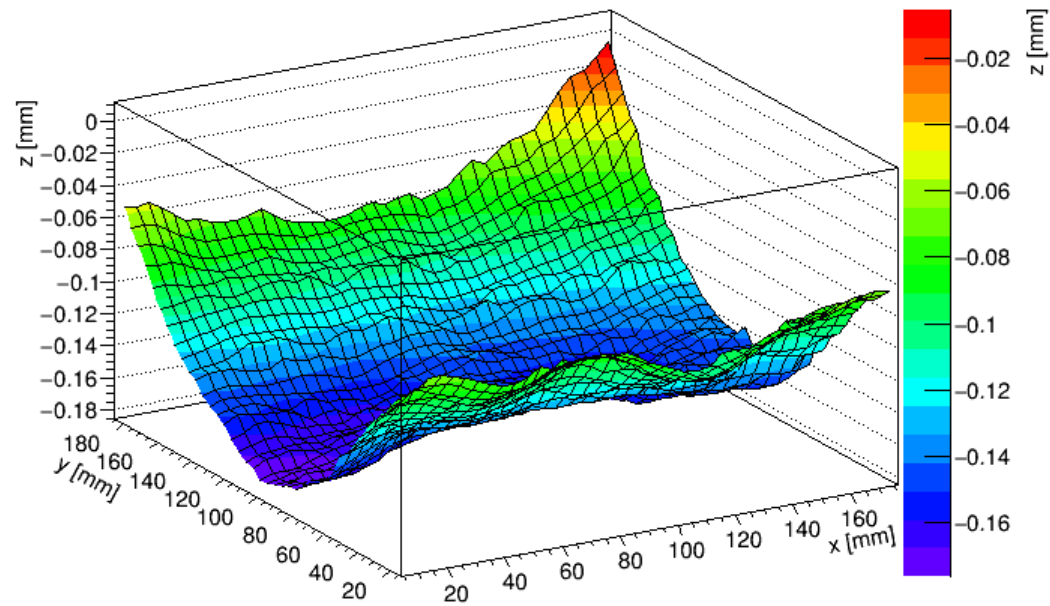
Yuichi Okugawa (PhD in Feb.)



A map to H.G.C. prototypes

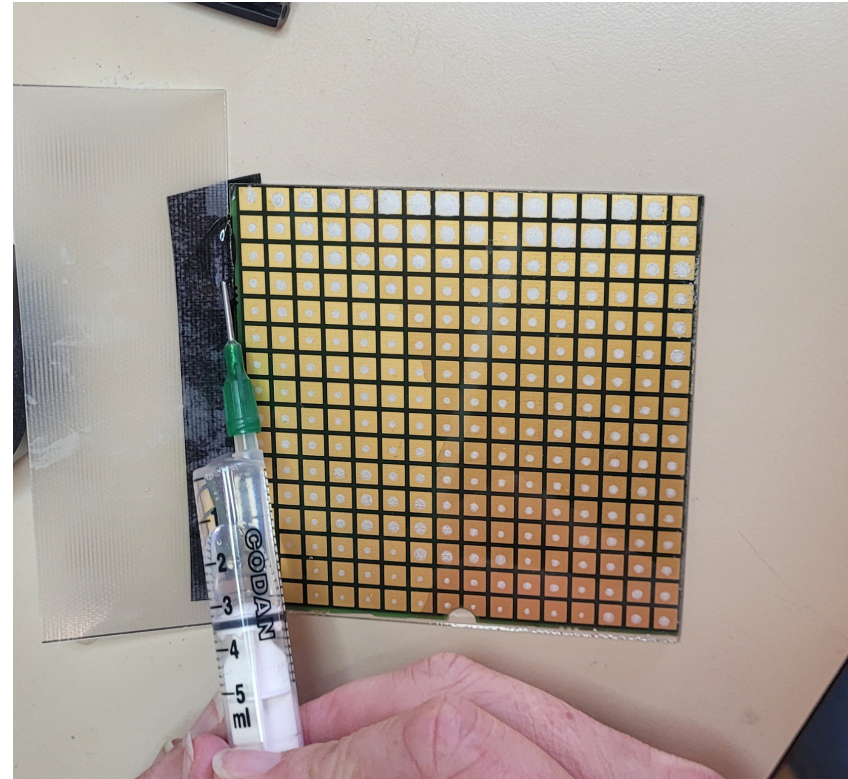


Control of PCB Deformation



- We suspect mechanical deformation of PCB to be at the origin of the delamination
- => Control PCB shape at different steps of manipulation (e.g. After heating during cabling)

“Underfill”



- Low viscosity glue flows around glue dots
- Development in close contact with Epotek
- Seems to work but requires second curing step
- First mechanical tests encouraging

“Double sided tape”



- Underfill “replaced” by double-sided tape
 - Holes with laser
- Encouraging first experience
- Close consultation with 3M

90 CALICE sensors received mid November

A probe card was designed and received in November from CERN (paid by TAU and IFIC).

December :

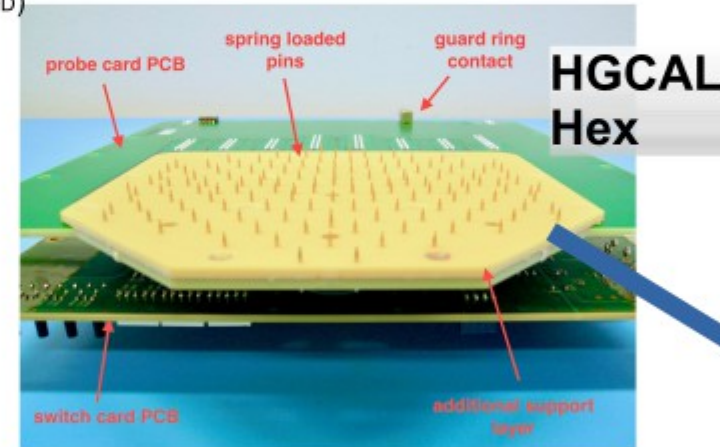
- modification of the probe station mechanics and installation of the probe card

January :

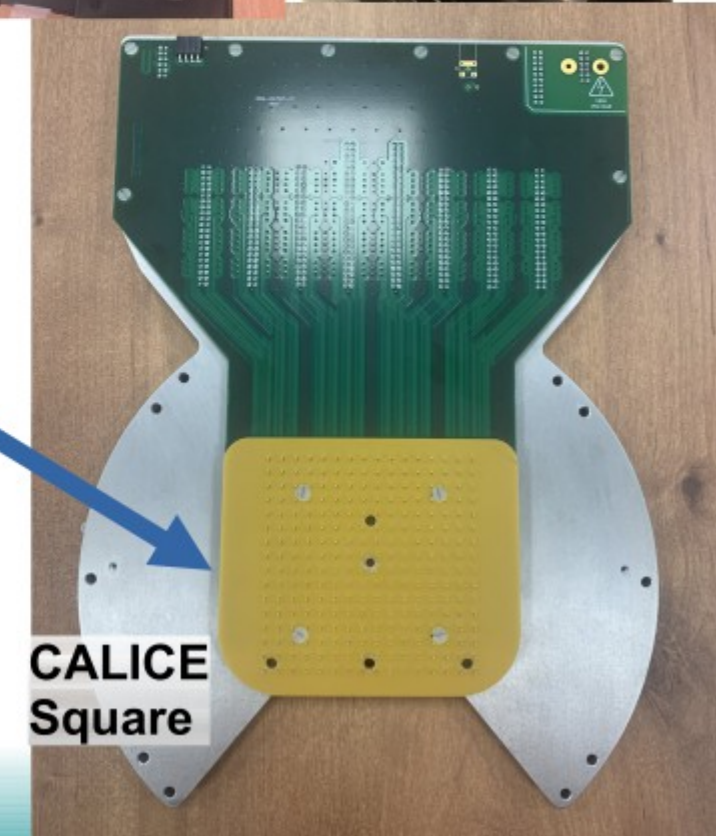
- we checked the LUT of the pins (pins number ^m DAQ channel)
- Started to test first sensors.
- Taking time to define the test procedure



System needed for electrical sensor characterisation in prototyping phase and for quality control in mass production (IV, CV, VBD, VFD, CFD)



241	242	243	244	245	246	247	248	249	250	251	252	253	254	255	256
225	226	227	228	229	230	231	232	233	234	235	236	237	238	239	240
209	210	211	212	213	214	215	216	217	218	219	220	221	222	223	224
193	194	195	196	197	198	199	200	201	202	203	204	205	206	207	208
177	178	179	180	181	182	183	184	185	186	187	188	189	190	191	192
161	162	163	164	165	166	167	168	169	170	171	172	173	174	175	176
145	146	147	148	149	150	151	152	153	154	155	156	157	158	159	160
129	130	131	132	133	134	135	136	137	138	139	140	141	142	143	144
113	114	115	116	117	118	119	120	121	122	123	124	125	126	127	128
97	98	99	100	101	102	103	104	105	106	107	108	109	110	111	112
81	82	83	84	85	86	87	88	89	90	91	92	93	94	95	96
65	66	67	68	69	70	71	72	73	74	75	76	77	78	79	80
49	50	51	52	53	54	55	56	57	58	59	60	61	62	63	64
33	34	35	36	37	38	39	40	41	42	43	44	45	46	47	48
17	18	19	20	21	22	23	24	25	26	27	28	29	30	31	32
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16



NanoCal

TB with nanocomposite scintillators
→ fast & rad-hard

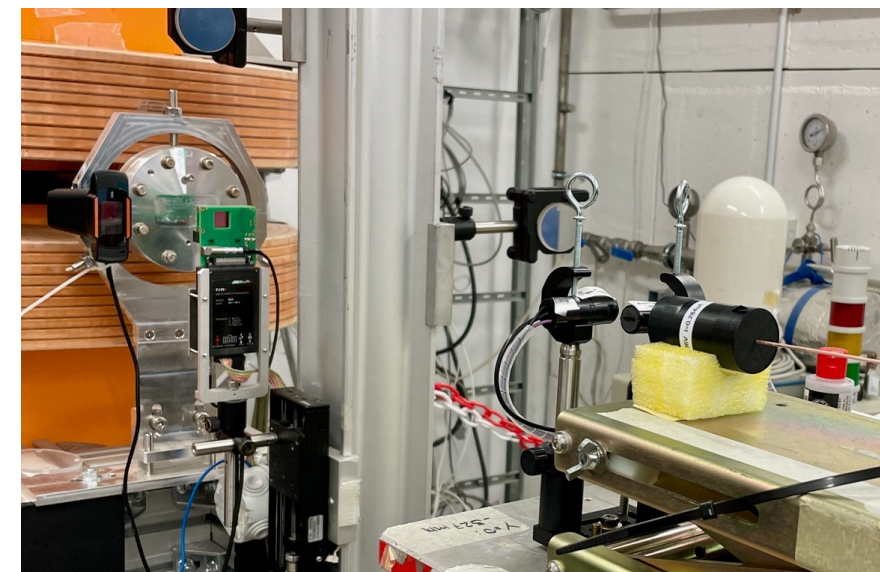
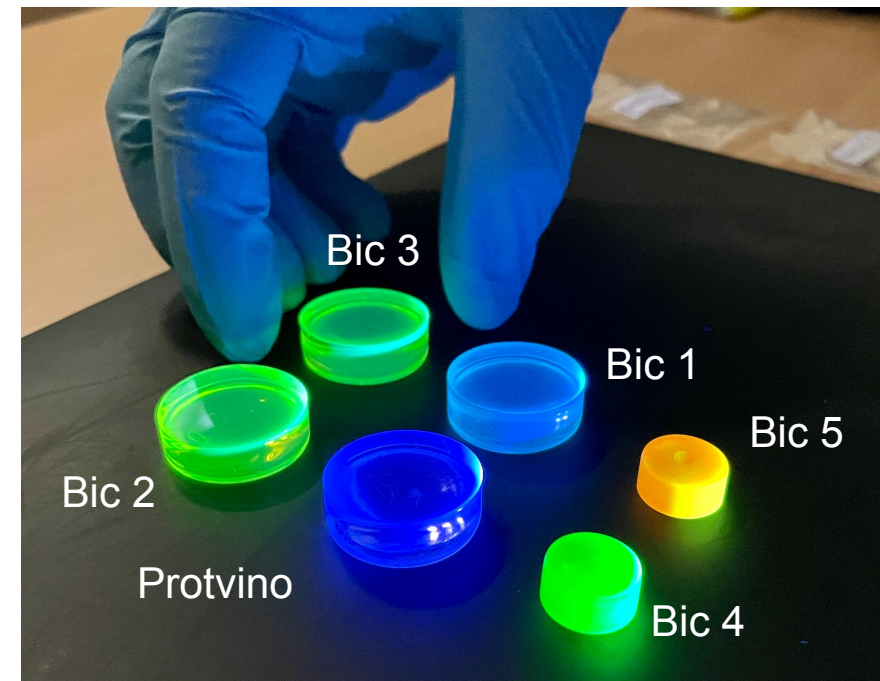
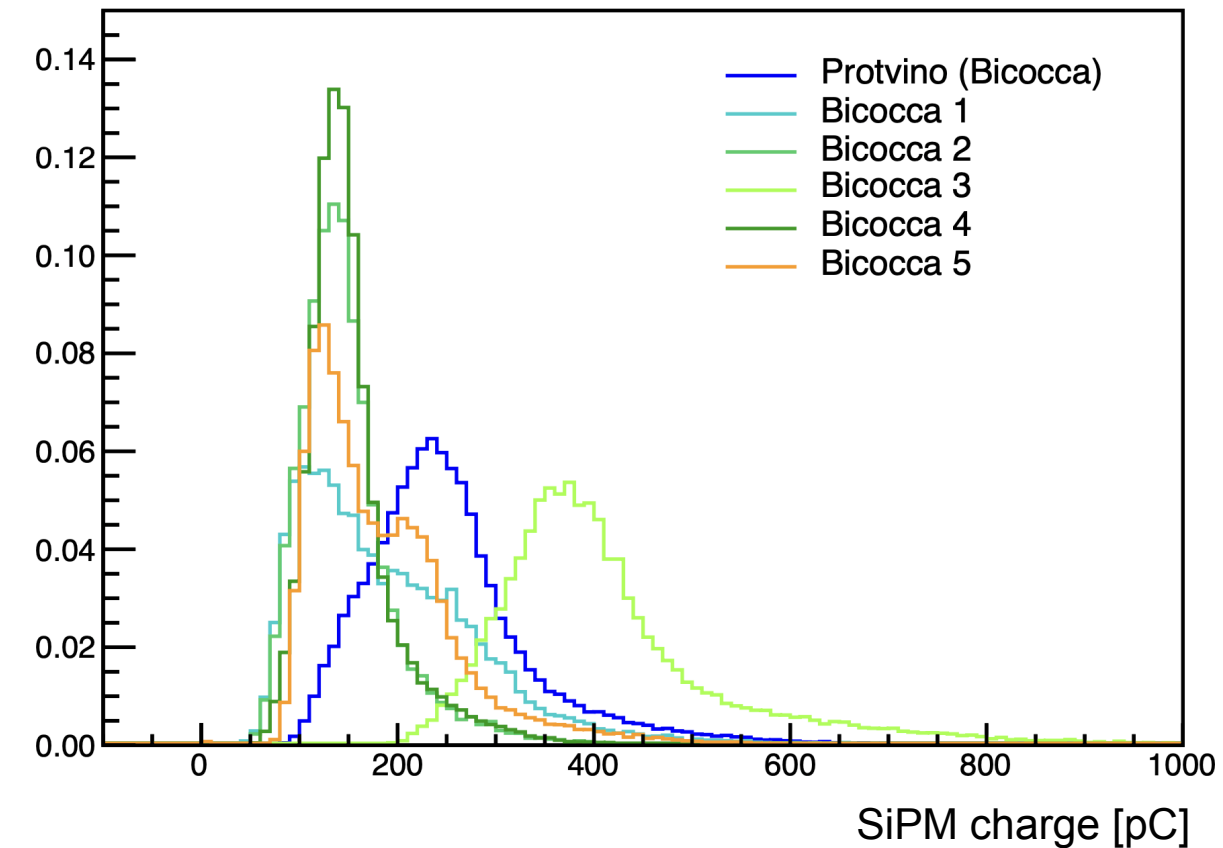
Tests with mip and e^-
@ CERN PS and Frascati BTF

- Protvino, Bic 1-3: custom-produced conventional organic scint.s
- Bic 4-5: nanocomposite scint.s

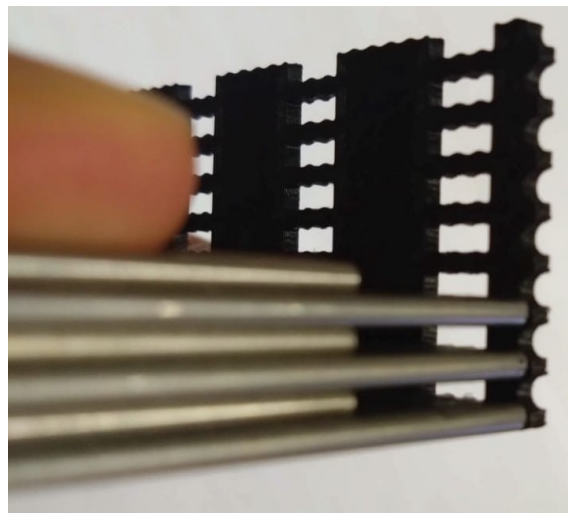
- Reference sample: 1.5% PTP + 0.04% POPOP in PVT (“Protvino”)
- Bicocca 4, 5: CsPbBr₃:Yb perovskites in PVT have ~50% light yield of ref. sample
First nanocomposites with good mip response!
- Bicocca 3: Coumarin-6 (green) scintillator with ~160% light yield of ref. sample

Many new samples to be tested in next BTF run

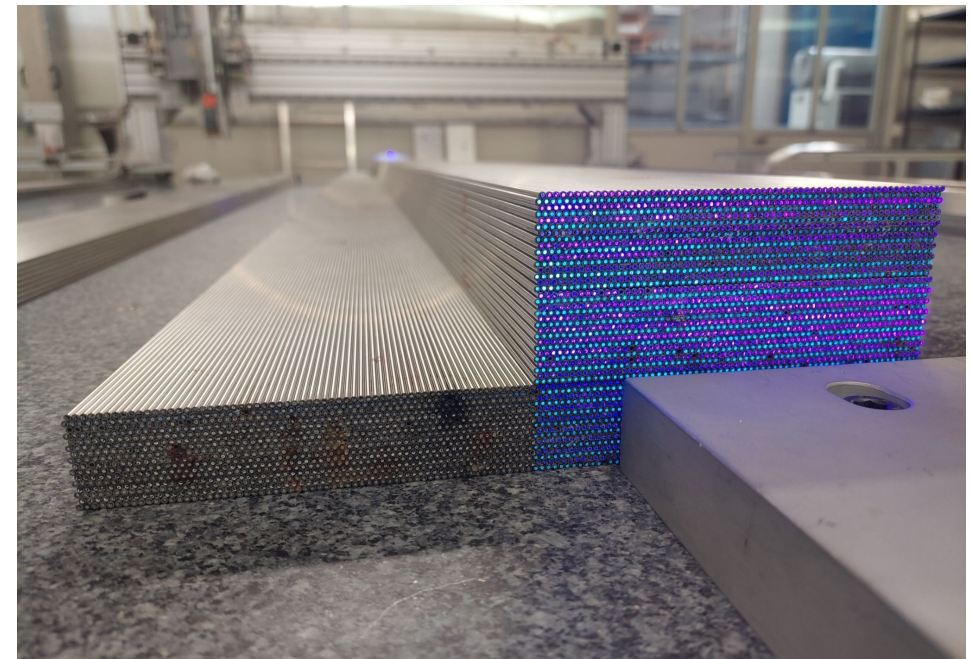
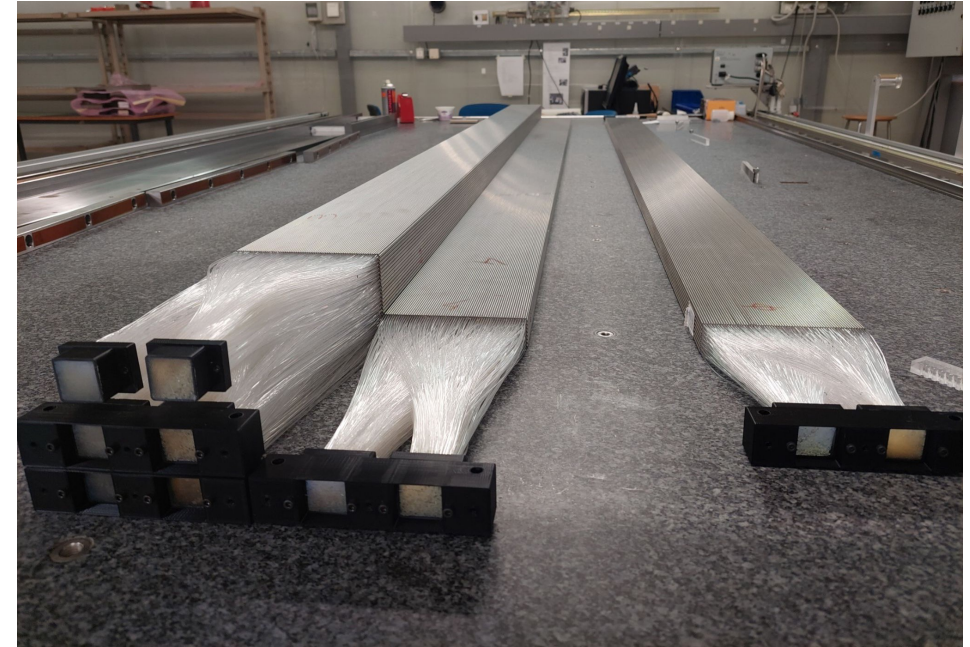
Normalised charge spectra
Single 450 MeV e^- events



- Started series production ...
- 18 MiniModules (MMs) completed
 - ~5-10% rejection for both sci-fibres and capillary tubes
- Estimated production rate: ~ 2 MMs / week
- SiPM readout: Integration tests w/ dummy components:



- Waiting for (hopefully) final pieces
- Aiming at beam test of few modules w/ PMT readout in 2024

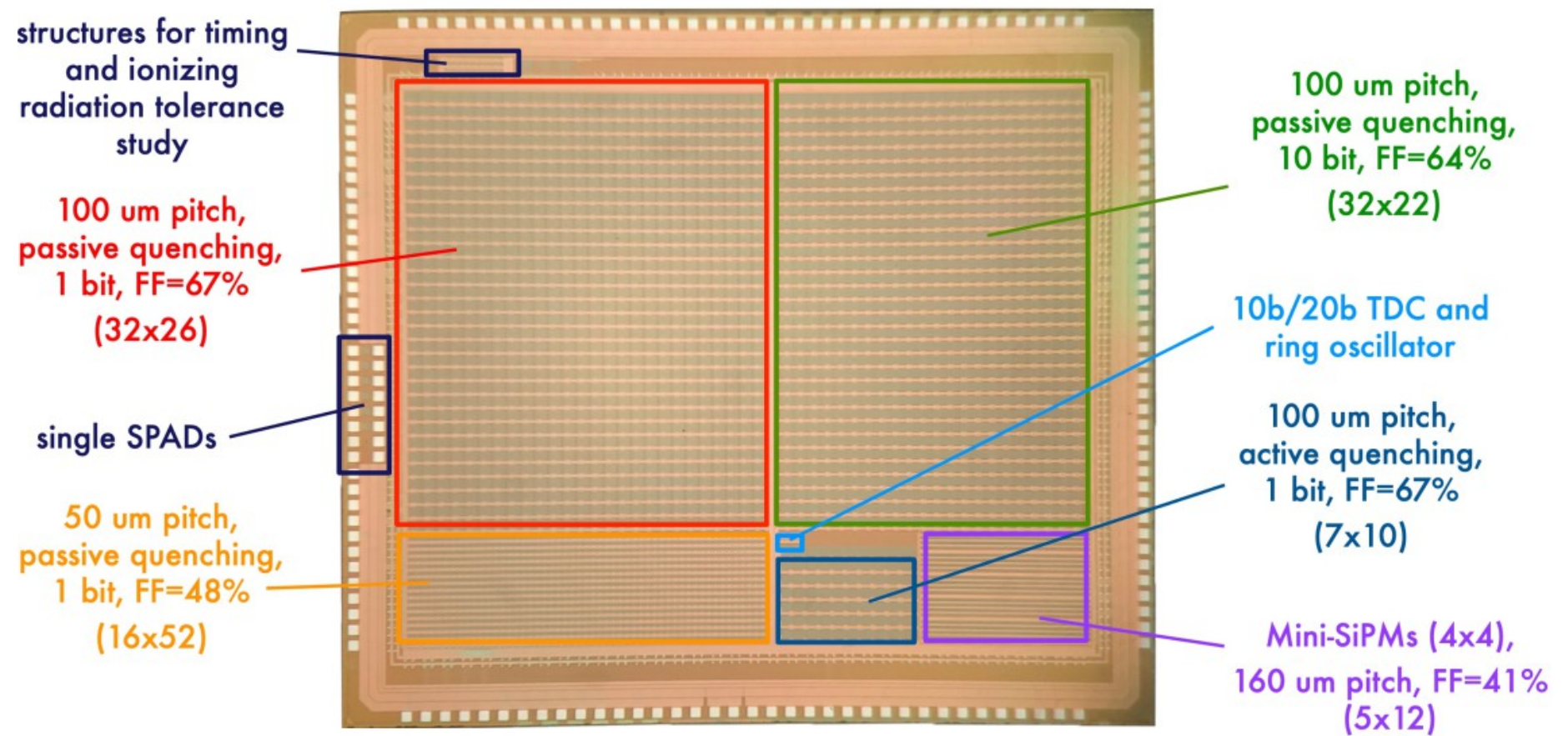


New:

R&D on digital-SiPMs
(SPAD arrays in 110 nm CMOS technology)

- FBK project
- Explore both fully digital & mixed analog+digital approach
- Develop demonstrator chip
8 × 1 mm² SiPMs

ASAP110LF chip – a technology characterization platform



ECFA DRD4 WP4.1 Solid State Photon Detectors Meeting – February 26, 2024

Training the next generation of African detector students

At the end of August, AIDAinnova detector scientists travelled to South Africa to organise an Instrumentation School.

By Antoine Le Gall (CERN)

The next generation of African detector scientists is eager to learn. Last August, just before the [TIPP conference](#), the [Instrumentation School in Particle, Nuclear and Medical Physics](#) took place at IThemba LABS in the Western Cape, in South Africa.

Over the course of one week, 25 MSc and PhD students coming from many different African countries – South Africa, Cameroon, Botswana, Egypt, etc. – took part in a series of lectures about particle detectors. Some of the students had already worked on detector experiments, at ATLAS and ALICE for instance, and were happy to learn about other types of detectors.

The school was punctuated by five sessions with hands-on experiments led by international instructors. “The students had the opportunity to cut their teeth on different detectors - silicon pixel ones, micro-pattern gas ones, cloud chambers, calorimeters, etc. –, operate their many parameters – calibration, signal – while using the same software and tools that we are using for real research”, explain Roman Poeschl from IJCLab. “This hands-on experience will be scaled up with real experiments”.

The school is sponsored by CERN, Germany’s DESY, France’s IJCLab and South Africa’s NRF. The first three labs all play a major role in AIDAinnova. “I am happy that we could use for the school hardware developed in the frame of AIDAinnova’s predecessor AIDA2020.”, adds Roman.

The positive feedback is testimonial to the importance to tie links with African institutes, some of which are already or are to become members of several experiments.

Link

Current Issue

On

Newsletter Issue

[October 2023](#)



- [Article realised with Antoine Le Gall](#)
- [Encouragement to try to get more on track articles](#)

Beneficiaries:

CAEN (Industry)
CERN
CNRS-IJCLab, CNRS-LLR, CNRS-LPNHE
CUNI
DESY
FBK (“Interface to industry”)
FZU
INFN-BO, INFN-LNF, INFN-PD, INFN-PG,
INFN-PV, INFN-TO
JSI
JGU
MPP-MPG
TAU
University of Bergen
University of Sussex
Vilnius University

Associated Partners:

FOTON (Industry)
GLASS2POWER (Industry)
Minsk
HZDR
Crytur